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HUA HONG SEMICONDUCTOR LIMITED

華虹半導體有限公司

(Incorporated in Hong Kong with limited liability)

Stock Code (01347)

News Release

Reports 2026 First Quarter Results

*All currency figures in this report are in US Dollars unless indicated otherwise.
The consolidated financial statements are prepared in accordance with HKFRS.*

Hong Kong Special Administrative Region of the People's Republic of China – May 14, 2026.

Hua Hong Semiconductor Limited (SEHK: 01347; SSE STAR MARKET: 688347) (the "Company"), a global, leading pure-play foundry, today announced its consolidated operational results for the quarter ending March 31, 2026.

First Quarter 2026 Highlights (Unaudited)

- Revenue was US\$660.9 million, 22.2% over 1Q 2025 and 0.2% above 4Q 2025.
- Gross margin was 13.0%, 3.8 percentage points over 1Q 2025 and flat with 4Q 2025.
- Net profit attributable to shareholders of the parent company was US\$20.9 million, 458.1% over 1Q 2025 and 19.9% above 4Q 2025.

Second Quarter 2026 Guidance

- We expect revenue to be approximately US\$690 million to US\$700 million.
- We expect gross margin to be in the range of 14% to 16%.

President's Message

Dr. Peng Bai, Chairman and President of Hua Hong Semiconductor, commented on the Company's 2026 first-quarter performance as follows:

"Hua Hong Semiconductor generated revenue of US\$660.9 million in the first quarter of 2026, a year-on-year increase of 22.2%. Gross margin stood at 13.0%, a year-on-year increase of 3.8 percentage points. Both figures were in line with our guidance. Net profit attributable to shareholders of the parent company amounted to US\$20.9 million, marking substantial year-on-year growth. Despite the rapid capacity ramp-up, the Company maintained high capacity utilization rates, with strong performance across all process technology platforms. MCU, standalone flash, and BCD products, delivered the highest growth rates. The Company's results were supported by sustained efforts in cost reduction and efficiency enhancement, and by a positive demand signal that started at the beginning of the quarter and became stronger over the course of the quarter."

Dr. Bai continued: "The global semiconductor industry is undergoing accelerated transformation as AI and related applications play an increasingly central role in market dynamics. The unmistakably positive impact of AI on worldwide semiconductor market demand, persistent uncertainties in the global supply chain landscape, make a more complex market picture that we are facing with. Hua Hong Semiconductor remains steadfast in pursuit of its key objective of becoming a foundry leader in specialty process technologies, with a core strategy of continuously focusing on market needs, strengthening process technology capabilities, and substantially increasing production capacity scale. In the first quarter, the ramp-up of our 12-inch capacity progressed steadily, with its revenue contribution rising to 62.7%, while our 8-inch production lines maintained sound profitability. Meanwhile, the proposed acquisition of Huali Micro has been accepted by the Shanghai Stock Exchange, entering the substantive review phase. The acquisition is currently progressing according to the established schedule and is expected to be completed in the second half of the year. Finally, as a veteran of the industry, I remain confident in a bright future for semiconductor industry globally and in China. I am fully committed to making Hua Hong Semiconductor an increasingly important player in the industry and deliver sustainable value to our shareholders."

Webcast/Conference Call Announcement

Date: Thursday, May 14, 2026

Time: 17:00 Hong Kong/Shanghai Time
05:00 EST

Presenters: Dr. Peng Bai, Chairman and President of the Company
Mr. Daniel Wang, Executive Vice President and Chief Financial Officer

Webcast: The call will be webcast live with audio and slides at:
https://www.huahonggrace.com/html/ir_calendar.php or
<https://edge.media-server.com/mmc/p/hzh37nq7>

(Note: registration is required to access the webcast.)

Dial-in Details: Please register in advance of the conference using the link provided below. Upon registering, you will be provided with participant dial-in numbers and personal PIN.

<https://register-conf.media-server.com/register/Blcb1a74a561af4a9393c1c207872566c1>

Important Note: Before the meeting starts, you will need the personal PIN to join the call. Please check and save the confirmation email after registering. For security reasons, please do not share your personal PIN with anyone else.

Replay: A recording will be available for replay at the below website about 2 hours after the event and will be available for 12 months.

https://www.huahonggrace.com/html/ir_calendar.php

About the Company

Hua Hong Semiconductor Limited (Stock Code: 688347.SH/ 01347.HK) (the "Company") is a global leading pure-play foundry with specialty technologies which offers a diverse array of wafer foundry and supporting services to its customers, implementing "8-inch + 12-inch" and advanced "Specialty IC + Power Discrete" development strategies. The Company focuses on continuous innovation of specialty technologies, including embedded/standalone non-volatile memory (NVM), power discrete, analog & power management, and logic & RF, supporting applications in emerging areas, such as new energy vehicles, green energy, and the Internet of Things. Of special note is the Company's outstanding quality control system that satisfies the strict requirements of automotive chip manufacturing. The Company is a member of the Hua Hong Group, which is an industrial group in China that owns mainstream "8-inch + 12-inch" advanced IC manufacturing process technologies.

The Company operates three 8-inch wafer fabrication facilities in Shanghai Jinqiao and Shanghai Zhangjiang. In addition, the Company has built two global leading 12-inch wafer fabrication facilities devoted to specialty processes in Wuxi National Hi-Tech District, one of which is the world's first 12-inch power semiconductor foundry.

For more information, please visit: www.huahonggrace.com.

Summary of Operating Results
(Amounts in US\$ thousands, except for EPS and operating data)

	1Q 2026 (Unaudited)	1Q 2025 (Unaudited)	4Q 2025 (Unaudited)	YoY Change	QoQ Change
Revenue	660,925	540,937	659,882	22.2 %	0.2 %
Gross profit	86,059	49,997	85,464	72.1 %	0.7 %
Gross margin	13.0 %	9.2 %	13.0 %	3.8	-
Operating expenses	(105,613)	(97,110)	(130,165)	8.8 %	(18.9)%
Other (loss) / income net	(2,448)	(8,294)	34,110	(70.5)%	(107.2)%
Loss before tax	(22,002)	(55,407)	(10,591)	(60.3)%	107.7 %
Income tax credit / (expense)	4,735	3,245	(8,069)	45.9 %	(158.7)%
Loss for the period	(17,267)	(52,162)	(18,660)	(66.9)%	(7.5)%
Net profit margin	(2.6)%	(9.6)%	(2.8)%	7.0	0.2
Attributable to:					
Owners of the parent	20,929	3,750	17,454	458.1 %	19.9 %
Non-controlling interests	(38,196)	(55,912)	(36,114)	(31.7)%	5.8 %
Earnings per share attributable to owners of the parent					
Basic	0.012	0.002	0.010	500.0 %	20.0 %
Diluted	0.012	0.002	0.010	500.0 %	20.0 %
Wafers shipped (in thousands 8" equivalent wafers)	1,453	1,231	1,448	18.0 %	0.3 %
Capacity utilization ¹	99.7%	102.7 %	103.8 %	(3.0)	(4.1)
ROE ²	1.2 %	0.4 %	1.2 %	0.8	-

First Quarter 2026

- Revenue was US\$660.9 million, 22.2% over 1Q 2025, primarily driven by increased wafer shipments and improved average selling price, and 0.2% over 4Q 2025.
- Gross margin was 13.0%, 3.8 percentage points over 1Q 2025, primarily driven by improved average selling price and cost reduction efforts, and flat with 4Q 2025.
- Operating expenses were US\$105.6 million, 8.8% over 1Q 2025, primarily due to increased operating expenses for the new production lines in Wuxi, and 18.9% lower than 4Q 2025, mainly due to decreased labor costs.
- Other loss net was US\$2.4 million, 70.5% lower than 1Q 2025, primarily due to foreign exchange gains versus foreign exchange losses in 1Q 2025, partially offset by decreased government subsidies, interest income, and increased finance costs. It was other income net of US\$34.1 million in 4Q 2025, mainly due to increased finance costs and decreased government subsidies.
- Income tax credit was US\$4.7 million, primarily due to a reversal of dividend withholding tax for 2025.
- Net loss for the period was US\$17.3 million, narrowed by 66.9% compared to 1Q 2025 and 7.5% compared to 4Q 2025.
- Net profit attributable to shareholders of the parent company was US\$20.9 million, 458.1% over 1Q 2025 and 19.9% above 4Q 2025.
- Basic earnings per share was US\$0.012.
- ROE (annualized) was 1.2%.

¹The capacity utilization is calculated based on average monthly equivalent wafers output divided by total estimated monthly capacity.

²Profit attributable to owners of the parent / weighted average net assets attributable to owners of the parent.

Analysis of Revenue

Revenue by service type	1Q 2026 US\$000 (Unaudited)	1Q 2026 % (Unaudited)	1Q 2025 US\$000 (Unaudited)	1Q 2025 % (Unaudited)	YoY Change US\$000	YoY Change %
Wafers	635,843	96.2 %	515,574	95.3 %	120,269	23.3 %
Others	25,082	3.8 %	25,363	4.7 %	(281)	(1.1)%
Total revenue	660,925	100.0 %	540,937	100.0 %	119,988	22.2 %

- 96.2% of total revenue was derived from the sale of semiconductor wafers in 1Q 2026.

Analysis of Revenue

Revenue by wafer size	1Q 2026 US\$000 (Unaudited)	1Q 2026 % (Unaudited)	1Q 2025 US\$000 (Unaudited)	1Q 2025 % (Unaudited)	YoY Change US\$000	YoY Change %
8" wafers	246,380	37.3 %	231,086	42.7 %	15,294	6.6 %
12" wafers	414,545	62.7 %	309,851	57.3 %	104,694	33.8 %
Total revenue	660,925	100.0 %	540,937	100.0 %	119,988	22.2 %

- Revenues from 8" wafers and 12" wafers were US\$246.4 million and US\$414.5 million, respectively, in 1Q 2026.

Analysis of Revenue

Revenue by geography	1Q 2026 US\$000 (Unaudited)	1Q 2026 % (Unaudited)	1Q 2025 US\$000 (Unaudited)	1Q 2025 % (Unaudited)	YoY Change US\$000	YoY Change %
China ³	525,209	79.5 %	442,458	81.8 %	82,751	18.7 %
North America ⁴	85,701	13.0 %	56,427	10.4 %	29,274	51.9 %
Other Asia ⁵	28,211	4.2 %	26,824	5.0 %	1,387	5.2 %
Europe	21,804	3.3 %	15,228	2.8 %	6,576	43.2 %
Total revenue	660,925	100.0 %	540,937	100.0 %	119,988	22.2 %

- *Revenue from China* was US\$525.2 million, contributing 79.5% of total revenue and an increase of 18.7% over 1Q 2025, mainly driven by increased demand for MCU, other PMIC, flash and IGBT products.
- *Revenue from North America* was US\$85.7 million, an increase of 51.9% over 1Q 2025, mainly driven by increased demand for other PMIC and MCU products.
- *Revenue from Other Asia* was US\$28.2 million, an increase of 5.2% over 1Q 2025, mainly driven by increased demand for MCU products, partially offset by decreased demand for super junction products.
- *Revenue from Europe* was US\$21.8 million, an increase of 43.2% over 1Q 2025, mainly driven by increased demand for smart card IC, IGBT and MCU products.

³Includes Chinese Mainland and Hong Kong.

⁴Includes a major customer in US that was acquired by an Europe headquartered company in 2020.

⁵Includes Taiwan, China and Japan.

Analysis of Revenue

Revenue by technology platform	1Q 2026 US\$000 (Unaudited)	1Q 2026 % (Unaudited)	1Q 2025 US\$000 (Unaudited)	1Q 2025 % (Unaudited)	YoY Change US\$000	YoY Change %
Embedded NVM	184,610	27.9 %	130,290	24.1 %	54,320	41.7 %
Standalone NVM	57,098	8.6 %	42,875	7.9 %	14,223	33.2 %
Power Discrete	170,919	25.9 %	162,751	30.1 %	8,168	5.0 %
Logic & RF	74,381	11.3 %	66,787	12.3 %	7,594	11.4 %
Analog & PM	173,917	26.3 %	138,234	25.6 %	35,683	25.8 %
Total revenue	660,925	100.0 %	540,937	100.0 %	119,988	22.2 %

- *Revenue from embedded NVM* was US\$184.6 million, an increase of 41.7% over 1Q 2025, mainly driven by increased demand for MCU and smart card ICs.
- *Revenue from standalone NVM* was US\$57.1 million, an increase of 33.2% over 1Q 2025, mainly driven by increased demand for flash products.
- *Revenue from power discrete* was US\$170.9 million, an increase of 5.0% over 1Q 2025, mainly driven by increased demand for IGBT and general MOSFET products, partially offset by decreased demand for super junction products.
- *Revenue from logic & RF* was US\$74.4 million, an increase of 11.4% over 1Q 2025, mainly driven by increased demand for logic and CIS products.
- *Revenue from analog & power management* was US\$173.9 million, an increase of 25.8% over 1Q 2025, mainly driven by increased demand for other PMIC products.

Analysis of Revenue

Revenue by process technology node	1Q 2026 US\$000 (Unaudited)	1Q 2026 % (Unaudited)	1Q 2025 US\$000 (Unaudited)	1Q 2025 % (Unaudited)	YoY Change US\$000	YoY Change %
≤65nm	179,374	27.1 %	124,280	23.0 %	55,094	44.3 %
90nm & 95nm	167,479	25.3 %	128,864	23.8 %	38,615	30.0 %
0.11μm & 0.13μm	70,751	10.7 %	54,059	10.0 %	16,692	30.9 %
0.15μm & 0.18μm	34,071	5.2 %	29,938	5.5 %	4,133	13.8 %
0.25μm	1,397	0.2 %	3,517	0.7 %	(2,120)	(60.3)%
≥0.35μm	207,853	31.5 %	200,279	37.0 %	7,574	3.8 %
Total revenue	660,925	100.0 %	540,937	100.0 %	119,988	22.2 %

- Revenue from 65nm and below technology nodes was US\$179.4 million, an increase of 44.3% over 1Q 2025, mainly driven by increased demand for other PMIC and flash products.
- Revenue from the 90nm & 95nm technology nodes was US\$167.5 million, an increase of 30.0% over 1Q 2025, mainly driven by increased demand for MCU, other PMIC and smart card ICs.
- Revenue from the 0.11μm & 0.13μm technology nodes was US\$70.8 million, an increase of 30.9% over 1Q 2025, mainly driven by increased demand for MCU products.
- Revenue from the 0.15μm & 0.18μm technology nodes was US\$34.1 million, an increase of 13.8% over 1Q 2025, mainly driven by increased demand for MCU and other PMIC products.
- Revenue from the 0.25μm technology node was US\$1.4 million, a decrease of 60.3% compared to 1Q 2025, mainly due to decreased demand for discrete and logic products.
- Revenue from the 0.35μm and above technology nodes was US\$207.9 million, an increase of 3.8% over 1Q 2025, mainly driven by increased demand for IGBT and general MOSFET products, partially offset by decreased demand for super junction products.

Analysis of Revenue

Revenue by end market distribution	1Q 2026 US\$000 (Unaudited)	1Q 2026 % (Unaudited)	1Q 2025 US\$000 (Unaudited)	1Q 2025 % (Unaudited)	YoY Change US\$000	YoY Change %
Consumer electronics	444,356	67.2 %	348,100	64.3 %	96,256	27.7 %
Industrial & automotive	143,150	21.7 %	119,878	22.2 %	23,272	19.4 %
Communications	62,667	9.5 %	65,264	12.1 %	(2,597)	(4.0)%
Computing	10,752	1.6 %	7,695	1.4 %	3,057	39.7 %
Total revenue	660,925	100.0 %	540,937	100.0 %	119,988	22.2 %

- *Revenue from consumer electronics*, our largest end market segment, contributed US\$444.4 million, reaching 67.2% of total revenue, an increase of 27.7% over 1Q 2025, mainly driven by increased demand for other PMIC, MCU and flash products.
- *Revenue from industrial & automotive* was US\$143.2 million, an increase of 19.4% over 1Q 2025, mainly driven by increased demand for MCU, smart card IC and IGBT products.
- *Revenue from communications* was US\$62.7 million, a decrease of 4.0% compared to 1Q 2025, mainly due to decreased demand for analog products.
- *Revenue from computing* was US\$10.8 million, an increase of 39.7% over 1Q 2025, mainly driven by increased demand for MCU products.

Capacity⁶ and Capacity Utilization

	1Q 2026 (Unaudited)	1Q 2025 (Unaudited)	4Q 2025 (Unaudited)
Total capacity (in thousands 8" equivalent wafers)	489	413	486
Overall capacity utilization	99.7%	102.7%	103.8%

- Monthly capacity was 489,000 8-inch equivalent wafers at the end of 1Q 2026. Overall capacity utilization was 99.7% in 1Q 2026.

Wafer Shipments

in thousands 8" equivalent wafers	1Q 2026 (Unaudited)	1Q 2025 (Unaudited)	4Q 2025 (Unaudited)	YoY Change	QoQ Change
Wafer shipments	1,453	1,231	1,448	18.0 %	0.3 %

- *Wafer shipments* were 1,453,000, an increase of 18.0% year over year, and 0.3% quarter over quarter.

⁶ Wafers per month at the end of the period, calculated on a 30-day basis for comparison purposes.

Operating Expenses Analysis

Amounts in US\$ thousands	1Q 2026 (Unaudited)	1Q 2025 (Unaudited)	4Q 2025 (Unaudited)	YoY Change	QoQ Change
Selling and distribution expenses	2,358	2,214	3,791	6.5 %	(37.8)%
Administrative expenses ⁷	103,255	94,896	126,374	8.8 %	(18.3)%
Operating expenses	105,613	97,110	130,165	8.8 %	(18.9)%

- *Operating expenses* were US\$105.6 million, 8.8% over 1Q 2025, primarily due to increased operating expenses for the new production lines in Wuxi, and 18.9% lower than 4Q 2025, mainly due to decreased labor costs.

Other (Loss) / Income Net Analysis

Amounts in US\$ thousands	1Q 2026 (Unaudited)	1Q 2025 (Unaudited)	4Q 2025 (Unaudited)	YoY Change	QoQ Change
Rental income	3,229	3,513	3,932	(8.1)%	(17.9)%
Interest income	10,394	15,619	15,228	(33.5)%	(31.7)%
Foreign exchange gains / (losses)	5,105	(16,199)	7,014	(131.5)%	(27.2)%
Share of profit of associates	153	652	1,261	(76.5)%	(87.9)%
Finance costs	(27,681)	(23,301)	(8,414)	18.8 %	229.0 %
Government subsidies	5,634	11,231	16,280	(49.8)%	(65.4)%
Others	718	191	(1,191)	275.9 %	(160.3)%
Other (loss) / income net	(2,448)	(8,294)	34,110	(70.5)%	(107.2)%

- *Other loss net* was US\$2.4 million, 70.5% lower than 1Q 2025, primarily due to foreign exchange gains versus foreign exchange losses in 1Q 2025, partially offset by decreased government subsidies, interest income, and increased finance costs. It was other income net of US\$34.1 million in 4Q 2025, mainly due to increased finance costs and decreased government subsidies.

⁷Administrative expenses include government grants recognized as an offset item.

Cash Flow Analysis

Amounts in US\$ thousands	1Q 2026 (Unaudited)	1Q 2025 (Unaudited)	4Q 2025 (Unaudited)	YoY Change	QoQ Change
Net cash flows generated from operating activities	130,427	50,186	246,026	159.9 %	(47.0)%
Net cash flows used in investing activities	(856,988)	(494,291)	(652,811)	73.4 %	31.3 %
Net cash flows generated from financing activities	638,664	59,137	1,361,101	980.0 %	(53.1)%
Effect of exchange rate changes	61,962	5,771	34,759	973.7 %	78.3 %
Net change in cash	(25,935)	(379,197)	989,075	(93.2)%	(102.6)%

- *Net cash flows generated from operating activities* was US\$130.4 million, 159.9% over 1Q 2025, mainly due to increased receipts from customers. It was 47.0% lower than 4Q 2025, largely due to decreased receipts of government grants and increased payments of labor costs.
- *Net cash flows used in investing activities* was US\$857.0 million, including US\$924.9 million investment in fixed assets, partially offset by US\$57.8 million decreased time deposits, US\$10.0 million interest income and US\$0.1 million receipts of disposal of equipment.
- *Net cash flows generated from financing activities* was US\$638.7 million, including US\$649.4 million proceeds from bank borrowings, and US\$3.3 million proceeds from share option exercises, partially offset by US\$12.1 million interest payments, US\$1.1 million lease payments, and US\$0.8 million of bank principal repayments.

Capital Structure

Amounts in US\$ thousands	31-Mar-2026 (Unaudited)	31-Dec-2025 (Audited)
Total assets	14,947,323	14,453,772
Total liabilities	5,662,963	5,289,541
Total equity	9,284,360	9,164,231
<i>Debt ratio</i> ⁸	37.9%	36.6%

Capital Expenditures

Amounts in US\$ thousands	1Q 2026 (Unaudited)	4Q 2025 (Unaudited)
Hua Hong 8"	38,725	74,527
Hua Hong 12"	886,146	558,847
Total	924,871	633,374

- *Capital expenditures* were US\$924.9 million in 1Q 2026, including US\$886.1 million for Hua Hong 12" and US\$38.7 million for Hua Hong 8".

⁸ Debt ratio is calculated based on total liabilities / total assets.

Liquidity

Amounts in US\$ thousands	31-Mar-2026 (Unaudited)	31-Dec-2025 (Audited)
Completed properties held for sale	218,918	215,511
Inventories	533,311	544,368
Trade and notes receivables	313,053	282,053
Prepayments, other receivables and other assets	661,570	561,328
Due from related parties	14,153	10,135
Restricted and time deposits	44,646	99,494
Cash and cash equivalents	4,867,873	4,893,808
Total current assets	6,653,524	6,606,697
Trade payables	270,387	330,370
Other payables and accruals	735,491	1,008,586
Interest-bearing bank borrowings	811,820	403,748
Lease liabilities	4,652	3,229
Government grants	90,371	89,049
Due to related parties	4,996	6,225
Income tax payable	17,912	15,014
Total current liabilities	1,935,629	1,856,221
Net working capital	4,717,895	4,750,476
<i>Quick ratio</i>	3.0x	3.1x
<i>Current ratio</i>	3.4x	3.6x
Trade and notes receivables turnover days	41	37
Inventories turnover days	84	83

- *Trade and notes receivables* increased from US\$282.1 million on 31 December 2025 to US\$313.1 million on 31 March 2026, mainly due to increased revenue.
- *Prepayments, other receivables and other assets* increased from US\$561.3 million on 31 December 2025 to US\$661.6 million on 31 March 2026, mainly due to increased value-added tax credit.
- *Restricted and time deposits* decreased from US\$99.5 million on 31 December 2025 to US\$44.6 million on 31 March 2026, mainly due to decreased time deposits.
- *Trade payables* decreased from US\$330.4 million on 31 December 2025 to US\$270.4 million on 31 March 2026, due to increased payments in the period.
- *Other payables and accruals* decreased from US\$1,008.6 million on 31 December 2025 to US\$735.5 million on 31 March 2026, mainly due to increased payments for capital expenditures in the period.
- *Interest-bearing bank borrowings* increased from US\$403.7 million on 31 December 2025 to US\$811.8 million on 31 March 2026, mainly due to the increase in the current portion of long term bank borrowings.
- On 31 March 2026, *net working capital* was US\$4,717.9 million and the *current ratio* was 3.4.
- *Trade and notes receivables turnover days* were 41.
- *Inventories turnover days* were 84.

Please visit Company's website at www.huahonggrace.com
for further details regarding recent announcements.

Hua Hong Semiconductor Limited
Condensed Consolidated Statements of Profit or Loss
(In US\$ Thousands Except Share Data)

	For the Three Months Ended		
	31-Mar-2026 (Unaudited)	31-Mar-2025 (Unaudited)	31-Dec-2025 (Unaudited)
Revenue	660,925	540,937	659,882
Cost of sales	(574,866)	(490,940)	(574,418)
Gross profit	86,059	49,997	85,464
Other income and gains	25,100	30,563	44,107
Fair value loss on an investment property	-	-	(2,844)
Selling and distribution expenses	(2,358)	(2,214)	(3,791)
Administrative expenses	(103,255)	(94,896)	(126,374)
Other expenses	(20)	(16,208)	-
Finance costs	(27,681)	(23,301)	(8,414)
Share of profit of associates	153	652	1,261
Loss before tax	(22,002)	(55,407)	(10,591)
Income tax credit / (expense)	4,735	3,245	(8,069)
Loss for the period	(17,267)	(52,162)	(18,660)
Attributable to:			
Owners of the parent	20,929	3,750	17,454
Non-controlling interests	(38,196)	(55,912)	(36,114)
Earnings per share attributable to owners of parent			
Basic	0.012	0.002	0.010
Diluted	0.012	0.002	0.010
Shares used in calculating basic earnings per share attributable to owners of parent	1,737,629,193	1,721,931,435	1,736,132,077
Shares used in calculating diluted earnings per share attributable to owners of parent	1,737,760,230	1,728,142,630	1,736,269,454

Hua Hong Semiconductor Limited
Condensed Consolidated Statements of Financial Position (In US\$ Thousands)

	As of		
	31-Mar-2026 (Unaudited)	31-Dec-2025 (Audited)	31-Mar-2025 (Unaudited)
ASSETS			
NON-CURRENT ASSETS			
Property, plant and equipment	7,105,886	6,676,442	5,967,555
Investment property	223,247	219,772	209,257
Right-of-use assets	64,125	64,482	76,359
Intangible assets	32,834	35,509	29,122
Investment in associates	152,751	150,222	140,650
Equity instruments designated at fair value through other comprehensive income	486,369	478,799	289,722
Long term prepayment	228,587	221,849	57,989
Deferred tax assets	-	-	380
Total non-current assets	8,293,799	7,847,075	6,771,034
CURRENT ASSETS			
Completed properties held for sale	218,918	215,511	221,061
Inventories	533,311	544,368	468,597
Trade and notes receivables	313,053	282,053	286,763
Prepayments, other receivables and other assets	661,570	561,328	411,207
Due from related parties	14,153	10,135	16,520
Restricted and time deposits	44,646	99,494	31,669
Cash and cash equivalents	4,867,873	4,893,808	4,079,935
Total current assets	6,653,524	6,606,697	5,515,752
CURRENT LIABILITIES			
Trade payables	270,387	330,370	255,321
Other payables and accruals	735,491	1,008,586	759,177
Interest-bearing bank borrowings	811,820	403,748	329,972
Lease liabilities	4,652	3,229	7,543
Government grants	90,371	89,049	57,700
Due to related parties	4,996	6,225	12,724
Income tax payable	17,912	15,014	18,620
Total current liabilities	1,935,629	1,856,221	1,441,057
NET CURRENT ASSETS	4,717,895	4,750,476	4,074,695
TOTAL ASSETS LESS CURRENT LIABILITIES	13,011,694	12,597,551	10,845,729
Non-current liabilities			
Interest-bearing bank borrowings	3,085,413	2,787,096	1,948,409
Lease liabilities	13,476	15,679	15,160
Deferred tax liabilities	24,463	35,964	1,498
Other long-term liabilities	603,982	594,581	-
Total non-current liabilities	3,727,334	3,433,320	1,965,067
Net assets	9,284,360	9,164,231	8,880,662
Equity and liabilities capital and reserves			
Share capital	4,987,537	4,987,482	4,957,182
Reserves	1,743,223	1,625,181	1,315,995
Equity attributable to the owners of the company	6,730,760	6,612,663	6,273,177
Non-controlling interests	2,553,600	2,551,568	2,607,485
Total equity	9,284,360	9,164,231	8,880,662

Hua Hong Semiconductor Limited
Condensed Consolidated Statement of Cash Flows (In US\$ Thousands)

	For the Three Months Ended		
	31-Mar-2026 (Unaudited)	31-Mar-2025 (Unaudited)	31-Dec-2025 (Unaudited)
Cash flows from operating activities:			
Loss before tax	(22,002)	(55,407)	(10,591)
Depreciation and amortization	214,606	172,126	195,876
Share of profit of associates	(153)	(652)	(1,261)
Changes in working capital and others	(62,024)	(65,881)	62,002
Net cash flows generated from operating activities	130,427	50,186	246,026
Cash flows from investing activities:			
Payments for property, plant and equipment and intangible assets	(924,871)	(510,851)	(633,374)
Investment in an equity instrument	-	-	(3,557)
Receipt of government grants of equipment	-	-	36,596
Decrease / (increase) of time deposits	57,794		(67,152)
Other cash flow generated from investing activities	10,089	16,560	14,676
Net cash flows used in investing activities	(856,988)	(494,291)	(652,811)
Cash flows from financing activities:			
New bank loans	649,364	860,985	919,025
Proceeds from issue of shares	3,343	13,077	4,740
Repayment of bank borrowings	(828)	(811,156)	(136,107)
Interest paid	(12,137)	(3,252)	(32,834)
Payment of lease liabilities	(1,078)	(517)	(428)
Receipt of government grants for interest expenses	-	-	12,124
Other cash flow generated from financing activities	-	-	594,581
Net cash flows generated from financing activities	638,664	59,137	1,361,101
Net (decrease) / increase in cash and cash equivalents	(87,897)	(384,968)	954,316
Cash and cash equivalents, beginning of period	4,893,808	4,459,132	3,904,733
Effects of exchange rate changes	61,962	5,771	34,759
Cash and cash equivalents, ending of period	4,867,873	4,079,935	4,893,808

As of the date of this announcement, the directors of the Company are:

Executive Directors

Peng Bai (Chairman and President)

Non-Executive Directors

Jun Ye

Guodong Sun

Bo Chen

Chengyan Xiong

Independent Non-Executive Directors

Stephen Tso Tung Chang

Kwai Huen Wong, JP

Songlin Feng

By order of the Board

Hua Hong Semiconductor Limited

Peng Bai

Chairman and Executive Director

Hong Kong SAR, PRC

May 14, 2026